Part Number: **SDM40E20LC-7 Date Code 0833+** p = package designator
Weight (mg): 9.17 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	14.02	1.28	1000000	140158
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.70	2.63	576500	165445
		Ni	7440-02-0	41.00%			410000	117662
		Mn	7439-96-5	0.60%			6000	1722
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	287
		Co	7440-48-4	0.50%			5000	1435
		Si	7440-21-3	0.15%			1500	430
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.13	0.10	1000000	11279
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.94	0.09	1000000	9436
Encapsulation	CEL-1620HF-9	Silica	60676-86-0	77.00%	49.57	4.54	770000	381703
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	-----	11.00%			110000	54529
		Basic Duromer:Phenolic resin (Compound of polymeric network)	-----	6.60%			66000	32717
		Misc.	system	5.00%			50000	24786
		Carbon black	1333-86-4	0.40%			4000	1983
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	2.86	0.26	750000	21418
		epoxy resin	Trade secret	20.00%			200000	5711
		curing agent & hardener	Trade secret	5.00%			50000	1428
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	10.91	0.26	1000000	27870
				Total	108.12	9.17		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)